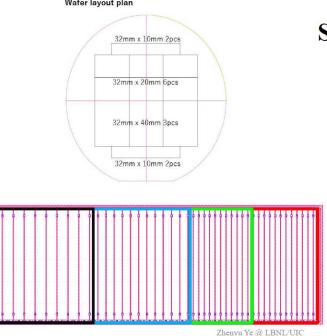
## New HPK Production – 2nd

- Strip sensor (UCSC, UIC, LBNL)
  - Four 30-um thick wafers, no significant issue,
  - Four 50-um thick wafers, only 33x11 mm "work": if the die have early breakdown than expected breakdown voltage (e.g. ~190V for 50um sensor) they just marked fail. Should re-test and judge by yourself



## **Strip Sensors**

Make ALL the strip sensors with

• 12xN strips with 500 um pitch, 1 cm length, 40 um width

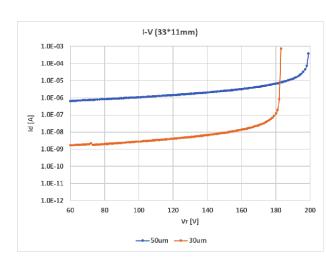
12xN strips with 500 um pitch, 1 cm length, 50 um width

12xN strips with 750 um pitch, 1 cm length, 50 um width

12xN strips with 1000 um pitch, 1 cm length, 50 um width

while the sensor area will still be 3.2\*1, 3.2\*2 or 3.2\*4 cm<sup>2</sup>

		OK chip					
	type	33*11(4pcs)	96	33*21(6pcs)	96	33*41(3pcs)	%
50um	W/No.1	1	25%	0	0%	0	0%
	W/No.2	4	100%	0	096	0	0%
	W/No.3	2	50%	0	0%	0	0%
	W/No.4	1	25%	0	0%	0	0%
	W/No.5	1	25%	0	0.96	0	0%
	W/No.6	3	75%	0	096	0	0%
	W/No.7	2	50%	0	0%	0	0%
	W/No.8	2	50%	0	096	0	0%
	W/No.9	2	50%	0	0%	0	0%
	W/No.10	1	25%	0	0%	0	0%
	W/No.11	2	50%	1	1796	0	0%
	W/No.12	1	25%	2	33%	0	096
30um -	W/No.13	3	75%	4	67%	2	67%
	W/No.14	3	75%	3	50%	0	0%
	W/No.15	4	100%	5	83%	2	67%
	W/No.16	3	75%	1	1796	0	096
	W/No.17	4	100%	5	83%	1	33%
	W/No.18	2	50%	2	33%	0	0%
	W/No.19	4	100%	5	83%	1	33%
	W/No.20	4	100%	3	50%	1	33%
	W/No.21	4	100%	3	50%	1	33%
	W/No.22	4	100%	5	83%	1	33%
	W/No.23	4	100%	5	83%	3	1009
	W/No.24	3	75%	5	83%	1	33%



- Pixel sensor (two 20 and two 30-um wafers)
  - Order placed by UIC on 12/6/2024. May take 3-4 months for sensor production and shipping by HPK, Japan

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# **Sensor Development PED Requests**

#### **LBNL**

- 1. Integrate and commission the beam telescope with 6 babyMOSS and 4 DC-LGAD+ETORC2 reference planes => 0.25-month physicist (in-kind), 1.5-month EE (PED)
- 2. Design mechanical, electrical, firmware and software interfaces to integrate new HPK sensors into the beam telescope => 0.25-month physicist (in-kind), 1.5-month EE (PED), 0.5-month tech (PED)
- 3. Contribute to data taking at test beam facilities  $\Rightarrow$  0.25-month physicist (in-kind)
- 4. Contribute to beam data analysis => 0.25-month physicist (in-kind)

#### **UIC**

- 1. Continue collaborating with other eRD112 Institutions on the telescope developments to integrate AC-LGAD sensors => Machine shop
- 2. Take part in commissioning and data-taking at FNAL's Test Beam Facility (or alternative testing sites, if necessary) => 0.2 FTE (in-kind)
- 3. Design and develop a cold-box setup for operations in a temperature-controlled environment and study of device functionality as a function of temperature and at its' extremes

# **Sensor Development PED Requests**

## LANL

- 1. Visit UCSC to perform irradiated pixel sensor performance studies => 0.05FTE (PED)
- 2. Participate beam test studies for pixel sensors at FNAL and JLab  $\Rightarrow$  0.05 FTE (PED) and 0.05 FTE (in-kind)
- 3. Contribute to offline analysis for pixel sensor bench and beam tests  $\Rightarrow$  0.1 FTE (PED) and 0.2 FTE (in-kind)
- 4. Work on a new LANSCE beam use proposal to request new irradiation tests for the relevant components of the ePIC HE TOF => If we will be granted the beam time, the shipping and equipment handling at LANL need some M&S funds to support.

## **Hiroshima University**

- 1. Selection of devices to be purchased and establishment of temperature control system;
- 2. Measurement of the temperature dependence of leak current and sensor performance with the radiation source;
- 3. Measurement of the temperature dependence of sensor performance by the test beam in Japan (KEK, Tohoku University)

# **Sensor Development PED Requests**

## **UCSC**

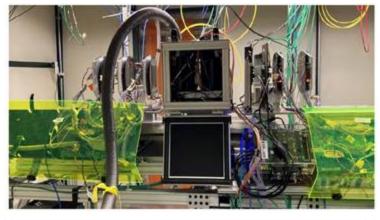
- 1. Revise the readout board for large sensor testing.
- 2. Test the first full-size HPK sensors using laser TCT systems.
- 3. Participate in test-beam efforts in  $2025 \Rightarrow 0.2$  FTE
- 4. Test irradiated sensors from IJS and FNAL ITA. Organize new irradiation campaign with the new full-size HPK sensors.
- 5. Run TCAD Sentaurus simulations to better understand the sensors behavior.

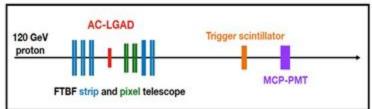
### **BNL**

?

# **Test Beam Requests**

- Fermilab Beam Test
  - FY25





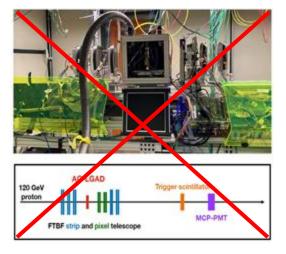
- Jlab Hall-D parasitic beam test
  - Feb 2025
    - Commission telescope setup, take data with HPK strip sensors
  - July 2025 (TBD)
    - ?

- KEK/Tohoku Univ beam test
  - April-September 2025

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# **Test Beam Requests**

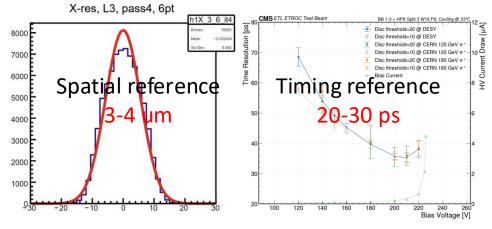
- Fermilab Beam Test
  - FY25



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